





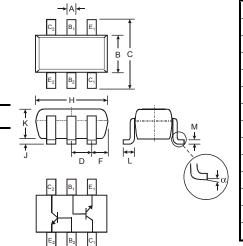
## **DUAL NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR**

## **Features**

- **Epitaxial Planar Die Construction**
- Ideal for Low Power Amplification and Switching
- Ultra-Small Surface Mount Package
- Qualified to AEC-Q101 Standards for High Reliability
- Lead Free/RoHS Compliant (Note 3)
- "Green" Device (Note 4 and 5)

## **Mechanical Data**

- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Terminal Connections: See Diagram Marking Information: K2X - See Page 4 Ordering & Date Code Information: See Page 4
- Weight: 0.006 grams (approximate)



SOT-363									
Dim	Min	Max							
Α	0.10	0.30							
В	1.15	1.35							
С	2.00	2.20							
D	0.65 Nominal								
F	0.30	0.40							
Н	1.80	2.20							
J	— 0.10								
K	0.90	1.00							
L	0.25	0.40							
М	0.10	0.25							
α	α 0° 8°								
All Din	nensions	in mm							

# **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Collector-Base Voltage		V <sub>CBO</sub>	60	V
Collector-Emitter Voltage		V <sub>CEO</sub>	40	V
Emitter-Base Voltage		V <sub>EBO</sub>	6.0	V
Collector Current - Continuous	(Note 1)	Ic	600	mA
Power Dissipation	(Note 1, 2)	P <sub>d</sub>	200	mW
Thermal Resistance, Junction to Ambient	(Note 1)	$R_{ heta JA}$	625	°C/W
Operating and Storage Temperature Range		T <sub>i</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

- 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- Maximum combined dissipation.
- No purposefully added lead.
- 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.
- 5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.



### **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)					
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	60		V	$I_C = 100 \mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	40		V	$I_C = 1.0 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	6.0		>	$I_E = 100 \mu A, I_C = 0$
Collector Cutoff Current	I <sub>CEX</sub>	_	100	nA	V <sub>CE</sub> = 35V, V <sub>EB(OFF)</sub> = 0.4V
Base Cutoff Current	$I_{BL}$	_	100	nA	$V_{CE} = 35V, V_{EB(OFF)} = 0.4V$
ON CHARACTERISTICS (Note 6)					
DC Current Gain	h <sub>FE</sub>	20 40 80 100 40	  300 	-	$I_C$ = 100µA, $V_{CE}$ = 1.0V $I_C$ = 1.0mA, $V_{CE}$ = 1.0V $I_C$ = 10mA, $V_{CE}$ = 1.0V $I_C$ = 150mA, $V_{CE}$ = 1.0V $I_C$ = 500mA, $V_{CE}$ = 2.0V
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	_	0.40 0.75	٧	$I_C = 150 \text{mA}, I_B = 15 \text{mA}$ $I_C = 500 \text{mA}, I_B = 50 \text{mA}$
Base-Emitter Saturation Voltage		SAT) 0.75 0.95 V		٧	$I_C = 150 \text{mA}, I_B = 15 \text{mA}$ $I_C = 500 \text{mA}, I_B = 50 \text{mA}$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	$C_{cb}$	_	6.5	pF	$V_{CB} = 5.0V$ , $f = 1.0MHz$ , $I_E = 0$
Input Capacitance	C <sub>eb</sub>	_	30	pF	$V_{EB} = 0.5V$ , $f = 1.0MHz$ , $I_{C} = 0$
Input Impedance	h <sub>ie</sub>	1.0	15	kΩ	
Voltage Feedback Ratio	h <sub>re</sub>	0.1	8.0	x 10 <sup>-4</sup>	V <sub>CE</sub> = 10V, I <sub>C</sub> = 1.0mA,
Small Signal Current Gain	h <sub>fe</sub>	40	500	_	f = 1.0kHz
Output Admittance	h <sub>oe</sub>	1.0	30	μS	
Current Gain-Bandwidth Product	f⊤	250	_	MHz	$V_{CE} = 10V, I_{C} = 20mA,$ f = 100MHz
SWITCHING CHARACTERISTICS					
Delay Time	t <sub>d</sub>	_	15	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA,
Rise Time	t <sub>r</sub>	_	20	ns	$V_{BE(off)} = 2.0V, I_{B1} = 15mA$
Storage Time	ts	_	225	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA,
Fall Time	t <sub>f</sub>	_	30	ns	$I_{B1} = I_{B2} = 15mA$

6. Short duration pulse test used to minimize self-heating effect.

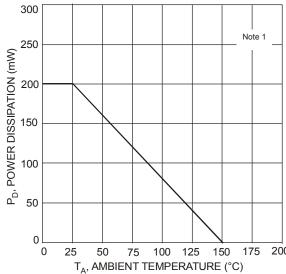


Fig. 1 Max Power Dissipation vs. Ambient Temperature

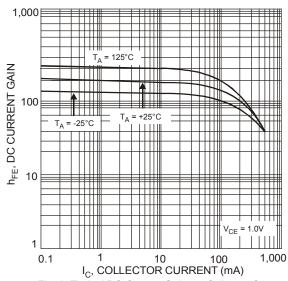
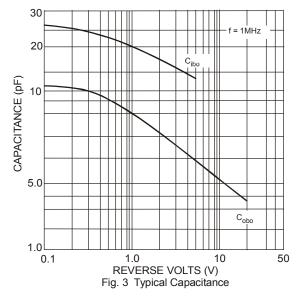


Fig. 2 Typical DC Current Gain vs. Collector Current





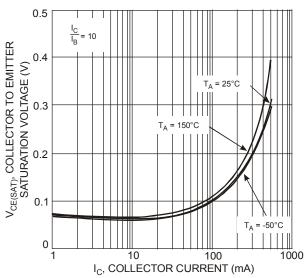


Fig. 5 Collector Emitter Saturation Voltage vs. Collector Current

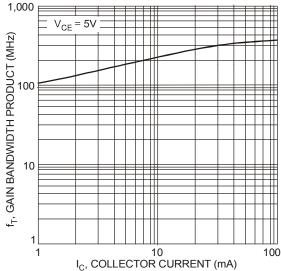


Fig. 7 Gain Bandwidth Product vs. Collector Current

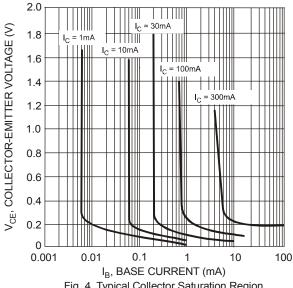


Fig. 4 Typical Collector Saturation Region

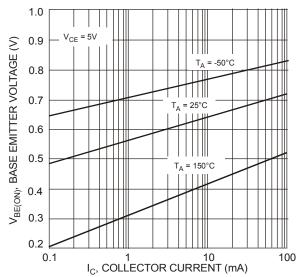


Fig. 6 Base Emitter Voltage vs. Collector Current

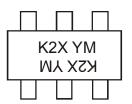


#### Ordering Information (Note 7)

Device	Packaging	Shipping
MMDT4401-7-F	SOT-363	3000/Tape & Reel

7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Marking Information**



K2X = Product Type Marking Code YM = Date Code Marking Y = Year ex: N = 2002 M = Month ex: 9 = September

Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	J	K	Г	М	Ν	Р	R	S	Т	C	V	W	Χ	Υ	Z

ĺ	Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
ĺ	Code	1	2	3	4	5	6	7	8	9	0	N	D

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